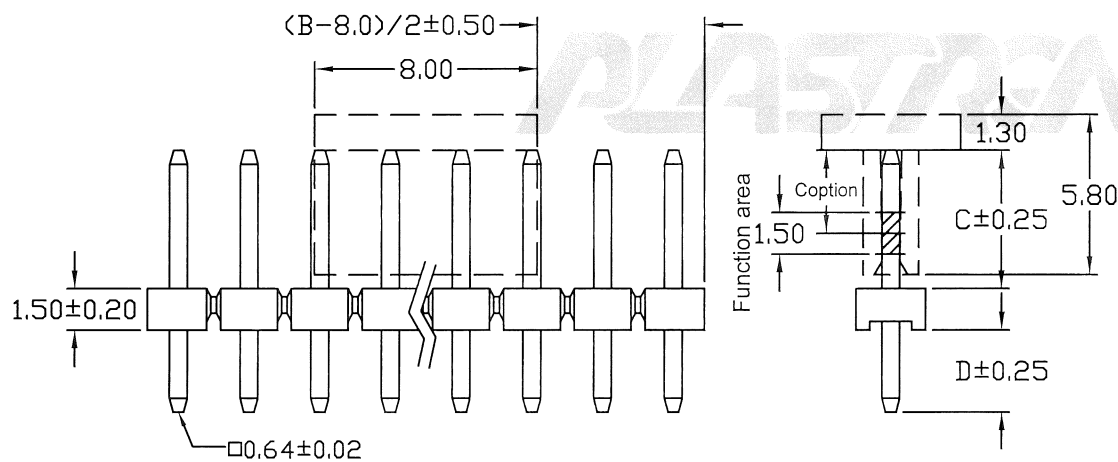
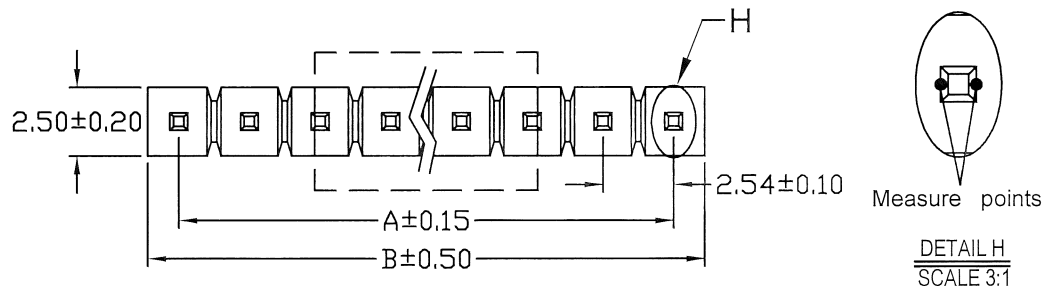


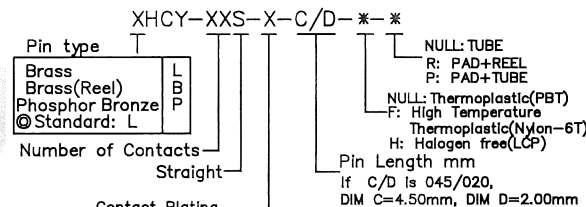
No. of Contacts	DIMENSIONS	
	A	B
1		2.54
2	2.54	5.08
3	5.08	7.62
4	7.62	10.16
5	10.16	12.70
6	12.70	15.24
7	15.24	17.78
8	17.78	20.32
9	20.32	22.86
10	22.86	25.40
11	25.40	27.94
12	27.94	30.48
13	30.48	33.02
14	33.02	35.56
15	35.56	38.10
16	38.10	40.64
17	40.64	43.18
18	43.18	45.72
19	45.72	48.26
20	48.26	50.80
21	50.80	53.34
22	53.34	55.88
23	55.88	58.42
24	58.42	60.96
25	60.96	63.50
26	63.50	66.04
27	66.04	68.58
28	68.58	71.12
29	71.12	73.66
30	73.66	76.20
31	76.20	78.74
32	78.74	81.28
33	81.28	83.82
34	83.82	86.36
35	86.36	88.90
36	88.90	91.44
37	91.44	93.98
38	93.98	96.52
39	96.52	99.06
40	99.06	101.60



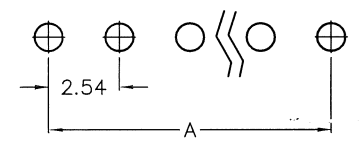
版次	ECN 编码	描述		设计/日期
20	CH10040098	改前	改后 PAD加长0.3mm	罗继明_2011/06/13
21	EL22090071		更换新图框	江蒙_2022/09/20

NOTES: (UNLESS OTHERWISE SPECIFIED)

- DIMENSION SHALL BE INTERPRETED PER ANSI Y14.5M.
- CONTACT RETENTION FORCE: 700g MIN, PER CONTACT.
- DURABILITY: 50 CYCLES MIN.
- RATING VOLTAGE: 30V A/DC.
- CURRENT RATING: 3 AMPERE.
- CONTACT RESISTANCE: 20 m ohms MAX, INITIAL.
- DIELECTRIC WITHSTANDING VOLTAGE: 500V AC rms./MINUTE.
- INSULATION RESISTANCE: 5000 Megohms MIN.
- OPERATING TEMPERATURE: -40°~+105°C.
- FINISH:
GOLD PLATED
◎ STANDARD: GOLD FLASH
◎ DUPLEX PLATING: GOLD PLATED ON CONTACT AREA, TIN PLATED ON SOLDER AREA
- HARMFUL MATERIAL SHOULD BE COMPLIANT TO DOC. "EI-0005" STANDARDS.
- PRODUCT NUMBER MATRIX:



Definition	Code
◎ Tin plated:	A
◎ Gold plated:	
flash B 15μ"	F
10μ"	E 30μ"
◎ Duplex plating:	
flash K 15μ"	P
10μ"	N 30μ"
◎ Standard: B	
All plating is lead free.	



RECOMMENDED PCB LAYOUT
(PCB TOLERANCE ±0.05)

	TOLERANCE TABLE		SCALE 1:1	DRAWN 江蒙	DATE 2022/09/20	DWG. NO. 600-0000-0515	TITLE	REV. 21
	X. ± 0.30	X.° ± 3°	UNIT mm	CHECK 李昌涛	DATE 2021/09/21	PARTS NO.(INTENDED USE) XHCY-XXS-X-C/D-*	CUSTOMER DRAWING	SHEET 1/1
	.X ± 0.25	.X° ± 2°	SIZE A4	APPROVE 江蒙	DATE 2022/09/21			